L Number	Hits	Search Text	DB	Time stamp
1	376933	retract\$5	USPAT;	2004/05/11 11:03
			US-PGPUB;	200 11 03/11 11:03
			EPO; JPO;	
l i			DERWENT;	
			IBM TDB	
2	2617875	wafer or substrate or pedestal or receiver	USPAT;	2004/05/11 11:03
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
		,	IBM_TDB	
3	6986	retract\$5 with (wafer or substrate or pedestal or receiver)	USPĀT;	2004/05/11 11:03
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
4	46343	(coating or sputtering or depositing) near2 apparatus	USPĀT;	2004/05/11 11:03
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	11	(retract\$5 with (wafer or substrate or pedestal or receiver)) same	USPAT;	2004/05/11 11:04
		((coating or sputtering or depositing) near2 apparatus)	US-PGPUB;	
			ЕРО; ЈРО;	
			DERWENT;	
			IBM_TDB	
6	263	(retract\$5 with (wafer or substrate or pedestal or receiver)) and ((coating	USPĀT;	2004/05/11 11:04
		or sputtering or depositing) near2 apparatus)	US-PGPUB;	,
			ЕРО; ЈРО;	
1			DERWENT,	
_			IBM_TDB	
7	252	((retract\$5 with (wafer or substrate or pedestal or receiver)) and	USPAT;	2004/05/11 11:07
		((coating or sputtering or depositing) near2 apparatus)) not ((retract\$5	US-PGPUB;	
		with (wafer or substrate or pedestal or receiver)) same ((coating or	ЕРО; ЈРО;	
		sputtering or depositing) near2 apparatus))	DERWENT;	
			IBM_TDB	